

In the Claims

Claim 1 (original): A semiconductor package, comprising:

a interposer construction containing only a single dielectric support member and comprising one or more conductive circuit traces contacting the single dielectric support member;

a semiconductor die electrically connected with at least one of the traces; and the circuit traces being between the semiconductor die and the dielectric support member.

Claim 2 (original): The semiconductor package of claim 1 wherein the dielectric support member is a photomask material.

Claim 3 (original): The semiconductor package of claim 1 wherein the dielectric support member is not a photomask material.

Claim 4 (original): The semiconductor package of claim 1 wherein the one or more circuit traces comprise copper.

Claim 5 (original): The semiconductor package of claim 1 wherein the dielectric support member is patterned to have openings extending therein, the package further comprising one or more electrically-conductive connectors within one or more of the openings and in electrical connection with the one or more circuit traces.

S:\mi22\2460\m01.doc

Claim 6 (original): The semiconductor package of claim 5 wherein the electrically-conductive connectors are solder balls.

Claim 7 (original): The semiconductor package of claim 1 wherein the dielectric support member is patterned to have openings extending therein, the package further comprising:

contact pads within one or more of the openings and in electrical connection with the one or more circuit traces; and

solder balls in electrical connection with the contact pads.

Claim 8 (original): The semiconductor package of claim 1 wherein:

the dielectric support member has a slit extending therethrough;

the dielectric support member has one or more openings extending therethrough for electrical connection to the one or more circuit traces; and

the electrical connection of the semiconductor die to said at least one of the circuit traces includes one or more wire bonds extending from the die, through the slit, and into at least one of the openings.

Claims 9-56 (canceled).

S:\ml22\2460\m01.doc